



Material Content Data Sheet



Sales Product Name		IPD60R3K3C6		Issued		4. July 2019		
MA#		MA005342314						
Package		PG-TO252-3-341		Weight*		387.12 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.000	0.26	0.26	2582	2582
leadframe	inorganic material	phosphorus	7723-14-0	0.069	0.02		178	
	non noble metal	iron	7439-89-6	0.229	0.06		592	
	non noble metal	copper	7440-50-8	228.946	59.14	59.22	591404	592174
	non noble metal	aluminium	7429-90-5	0.421	0.11	0.11	1086	1086
wire	non noble metal	aluminium	7429-90-5	0.421	0.11	0.11	1086	1086
encapsulation	organic material	carbon black	1333-86-4	0.395	0.10		1020	
	plastics	epoxy resin	-	11.975	3.09		30934	
	inorganic material	silicondioxide	60676-86-0	119.224	30.80	33.99	307976	339930
leadfinish	non noble metal	tin	7440-31-5	3.740	0.97	0.97	9661	9661
plating	non noble metal	nickel	7440-02-0	0.509	0.13	0.13	1314	1314
solder	non noble metal	tin	7440-31-5	0.028	0.01		73	
	noble metal	silver	7440-22-4	0.035	0.01		91	
	non noble metal	lead	7439-92-1	1.349	0.35	0.37	3485	3649
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		15	
	non noble metal	iron	7439-89-6	0.019	0.00		50	
	non noble metal	copper	7440-50-8	19.177	4.95	4.95	49539	49604
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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